

**CRYSTAL OSCILLATOR (Programmable)
SPREAD SPECTRUM
OUTPUT: CMOS**



Product Number
SG-9101CA: X1G005301xxxx00
SG-9101CB: X1G005311xxxx00
SG-9101CE: X1G005321xxxx00
SG-9101CG: X1G005291xxxx00

SG-9101 series

- Frequency range : 0.67 MHz to 170 MHz (1 ppm Step)
- Supply voltage : 1.62 V to 3.63 V
- Function : Output enable (OE) or Standby (\overline{ST})
- Configurable spread spectrum settings:
 2 kinds of spread type, 6 kinds of spread width
 4 kinds of modulation frequency, 3 kinds of spread profile
- PLL technology to enable short lead time
- Available field oscillator programmer "SG-Writer II"



Specifications (characteristics)

| Item | Symbol | Specifications | | | | Conditions/Remarks | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
|--|-----------------------|--|------------------|------------------|--------------------------------------|---|--|----------------|-----------------|----|----|----|----|--|-----------------|------|------|------|------|-----------------|-----|-----|-----|-----|-----------------------------------|-----------------|------|------|------|------|-----------------|-----|-----|-----|-----|------|-----------------|------|------|------|------|-----------------|-----|-----|-----|
| Supply voltage | V _{CC} | 1.80 V Typ. | | 2.50 V Typ. | 3.30 V Typ. | | - | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | 1.62 V to 1.98 V | 1.98 V to 2.20 V | 2.20 V to 2.80 V | 2.70 V to 3.63 V | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Output frequency range | f _o | 0.67 MHz to 170 MHz | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Storage temperature | T _{stg} | -40 °C to +125 °C | | | | Storage as single product. | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Operating temperature | T _{use} | -40 °C to +85 °C | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | -40 °C to +105 °C | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Frequency tolerance ^{*1} | f _{tol} | ±50 × 10 ⁻⁶ | | | | Average frequency of 1s gate time. | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Current consumption | I _{CC} | 3.4 mA Max. | 3.5 mA Max. | 3.6 mA Max. | 3.7 mA Max. | T _{use} = +105 °C | No load, f _o = 20 MHz | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | 2.9 mA Typ. | | 3.0 mA Typ. | 3.2 mA Typ. | T _{use} = +25 °C | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | 5.7 mA Max. | 6.0 mA Max. | 6.9 mA Max. | 8.3 mA Max. | T _{use} = +105 °C | No load, f _o = 170 MHz | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | 4.9 mA Typ. | | 5.9 mA Typ. | 7.0 mA Typ. | T _{use} = +25 °C | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Output disable current | I _{dis} | 3.4 mA Max. | 3.4 mA Max. | 3.5 mA Max. | 3.7 mA Max. | OE = GND, f _o = 170 MHz | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Standby current | I _{std} | 0.9 μA Max. | 1.0 μA Max. | 1.5 μA Max. | 2.5 μA Max. | T _{use} = +105 °C | \overline{ST} = GND | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | 0.3 μA Typ. | 0.4 μA Typ. | 0.5 μA Typ. | 1.1 μA Typ. | T _{use} = +25 °C | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Symmetry | SYM | 45 % to 55 % | | | | 50 % V _{CC} Level | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Output voltage (DC characteristics) | V _{OH} | 90 % V _{CC} Min. | | | | I _{OH} /I _{OL} Conditions [mA] | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | V _{OL} | 10 % V _{CC} Max. | | | | <table border="1"> <thead> <tr> <th>Rise/Fall time</th> <th>V_{CC}</th> <th>*A</th> <th>*B</th> <th>*C</th> <th>*D</th> </tr> </thead> <tbody> <tr> <td rowspan="2">Default (f_o > 40 MHz), Fast</td> <td>I_{OH}</td> <td>-2.5</td> <td>-3.5</td> <td>-4.0</td> <td>-5.0</td> </tr> <tr> <td>I_{OL}</td> <td>2.5</td> <td>3.5</td> <td>4.0</td> <td>5.0</td> </tr> <tr> <td rowspan="2">Default (f_o ≤ 40 MHz)</td> <td>I_{OH}</td> <td>-1.5</td> <td>-2.0</td> <td>-2.5</td> <td>-3.0</td> </tr> <tr> <td>I_{OL}</td> <td>1.5</td> <td>2.0</td> <td>2.5</td> <td>3.0</td> </tr> <tr> <td rowspan="2">Slow</td> <td>I_{OH}</td> <td>-1.0</td> <td>-1.5</td> <td>-2.0</td> <td>-2.5</td> </tr> <tr> <td>I_{OL}</td> <td>1.0</td> <td>1.5</td> <td>2.0</td> <td>2.5</td> </tr> </tbody> </table> | | Rise/Fall time | V _{CC} | *A | *B | *C | *D | Default (f _o > 40 MHz), Fast | I _{OH} | -2.5 | -3.5 | -4.0 | -5.0 | I _{OL} | 2.5 | 3.5 | 4.0 | 5.0 | Default (f _o ≤ 40 MHz) | I _{OH} | -1.5 | -2.0 | -2.5 | -3.0 | I _{OL} | 1.5 | 2.0 | 2.5 | 3.0 | Slow | I _{OH} | -1.0 | -1.5 | -2.0 | -2.5 | I _{OL} | 1.0 | 1.5 | 2.0 |
| Rise/Fall time | V _{CC} | *A | *B | *C | *D | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Default (f _o > 40 MHz), Fast | I _{OH} | -2.5 | -3.5 | -4.0 | -5.0 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | I _{OL} | 2.5 | 3.5 | 4.0 | 5.0 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Default (f _o ≤ 40 MHz) | I _{OH} | -1.5 | -2.0 | -2.5 | -3.0 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | I _{OL} | 1.5 | 2.0 | 2.5 | 3.0 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Slow | I _{OH} | -1.0 | -1.5 | -2.0 | -2.5 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | I _{OL} | 1.0 | 1.5 | 2.0 | 2.5 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Output load condition | L _{CMOS} | 15 pF Max. | | | | - | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Input voltage | V _{IH} | 70 % V _{CC} Min. | | | | OE or \overline{ST} | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | V _{IL} | 30 % V _{CC} Max. | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Rise time / Fall time | Default / Fast / Slow | tr/tf | 3.0 ns Max. | | f _o > 40 MHz | | 20 % - 80 % V _{CC} , L _{CMOS} = 15 pF | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | | 6.0 ns Max. | | f _o ≤ 40 MHz | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | | 3.0 ns Max. | | f _o = 0.67 MHz to 170 MHz | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | | | 10.0 ns Max. | | f _o = 0.67 MHz to 20 MHz | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Output disable time (OE) | tstp_oe | 1 μs Max. | | | | Measured from the time OE or \overline{ST} pin crosses 30 % V _{CC} | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Output disable time (ST) | tstp_st | 1 μs Max. | | | | Measured from the time OE pin crosses 70 % V _{CC} | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Output enable time (OE) | tsta_oe | 1 μs Max. | | | | Measured from the time \overline{ST} pin crosses 70 % V _{CC} | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Output enable time (ST) | tsta_st | 3 ms Max. | | | | Measured from the time V _{CC} reaches its rated minimum value, 1.62 V | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Start-up time | t _{str} | 3 ms Max. | | | | Measured from the time V _{CC} reaches its rated minimum value, 1.62 V | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Frequency aging | f _{age} | This is included in frequency tolerance specification. | | | | +25 °C, first year | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |

*1 Frequency tolerance includes initial frequency tolerance, frequency / temperature characteristics, frequency / voltage coefficient, frequency / load coefficient and frequency aging (+25 °C, 1 year).

Pin description

| Pin | Name | I/O type | Function | |
|-----|-----------------|----------|---------------|--|
| 1 | OE | Input | Output enable | High ^{*2} : Specified frequency output from OUT pin Low: Out pin is low (weak pull down), only output driver is disabled. |
| | \overline{ST} | Input | Standby | High ^{*2} : Specified frequency output from OUT pin Low: Out pin is low (weak pull down), Device goes to standby mode. Supply current reduces to the least as I _{std} . |
| 2 | GND | Power | Ground | |
| 3 | OUT | Output | Clock output | |
| 4 | V _{CC} | Power | Power supply | |

*2 Please do not use the OE/ST terminal in the open state.



Product Name

SG-9101CG 170.000000MHz C 20 P H A A A
① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩

- ① Model
- ② Package type
- ③ Frequency
- ④ Spread type
- ⑤ Spread width
- ⑥ Function
- ⑦ Operating temperature
- ⑧ Modulation frequency
- ⑨ Spread profile
- ⑩ Rise/Fall time

| ② Package type | |
|----------------|-----------------|
| CG | 2.5 mm × 2.0 mm |
| CE | 3.2 mm × 2.5 mm |
| CB | 5.0 mm × 3.2 mm |
| CA | 7.0 mm × 5.0 mm |

| ④ Spread type | |
|---------------|---------------|
| C | Center spread |
| D | Down spread |

| ⑤ Spread width | | |
|----------------|---------------|-------------|
| | Center spread | Down spread |
| 02 | ±0.25 % | |
| 05 | ±0.5 % | -0.5 % |
| 07 | ±0.75 % | |
| 10 | ±1.0 % | -1.0 % |
| 15 | ±1.5 % | -1.5 % |
| 20 | ±2.0 % | -2.0 % |
| 30 | | -3.0 % |
| 40 | | -4.0 % |

| ⑧ Modulation frequency | |
|------------------------|--------------------|
| A | 25.4 kHz (Default) |
| B | 12.7 kHz |
| C | 8.5 kHz |
| D | 6.3 kHz |

| ⑨ Spread profile | |
|------------------|------------------------|
| A | Hershey-kiss (Default) |
| B | Sine-wave |
| C | Triangle |

| ⑥ Function | |
|------------|---------------|
| P | Output enable |
| S | Standby |

| ⑩ Rise/Fall time | |
|------------------|---------|
| A | Default |
| B | Fast |
| C | Slow |

| ⑦ Operating temperature | |
|-------------------------|-------------------|
| G | -40 °C to +85 °C |
| H | -40 °C to +105 °C |

External dimensions

(Unit: mm)



Footprint (Recommended)

(Unit: mm)



Notes:

In order to achieve optimum jitter performance, the 0.1 μF capacitor between V_{CC} and GND should be placed. It is also recommended that the capacitors are placed on the device side of the PCB, as close to the device as possible and connected together with short wiring pattern.

PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

WORKING FOR HIGH QUALITY

In order provide high quality and reliable products and services than meet customer needs, Seiko Epson made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired IATF 16949 certification that is requested strongly by major automotive manufacturers as standard.

IATF 16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

► Explanation of the mark that are using it for the catalog

| | |
|---|---|
|  | ► Pb free. |
|  | ► Complies with EU RoHS directive. *About the products without the Pb-free mark. Contains Pb in products exempted by EU RoHS directive. (Contains Pb in sealing glass, high melting temperature type solder or other.) |
|  | ► Designed for automotive applications such as Car Multimedia, Body Electronics, Remote Keyless Entry etc. |
|  | ► Designed for automotive applications related to driving safety (Engine Control Unit, Air Bag, ESC etc). |

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